

Amendment

Please amend the above-identified application as follows.

In The Claims

Please amend claim 2:

2. (Amended) A method for soldering plastic flex circuits by diode laser,
A) said method comprising the steps of:

providing at least a first flex circuit and a second flex circuit composed of polymer flex substrate, each having a top and bottom side, and each with at least one contact trace embedded therein;

providing an area of solder on said at least one contact trace of at least one of said first flex circuit or said second flex circuit;

positioning said first flex circuit and said second flex circuit such that said at least one contact trace of each flex circuit are in substantial alignment;

positioning at least one laser beam to heat said at least one contact trace to melt said solder and fuse said contacts; and

moving said laser beam across said flex circuits.

Please cancel claims 1 and 20 without prejudice.